

Application Number 10/047,272
Amendment dated January 20, 2004
Reply to Office Action of November 19, 2003

Amendments to the Claims

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims

1. (Currently Amended) A packaging structure for packaging a plurality of semiconductor chips, the packaging structure comprising a film to which the plurality of semiconductor chips are directly mounted, wherein the film is folded in a predetermined direction so as to package the plurality of semiconductor chips in one package.
2. (Original) The packaging structure as claimed in claim 1, wherein the film comprises:
an insulating film; and
a conductive pattern formed on the surface of the insulating film.
3. (Original) The packaging structure as claimed in claim 1, wherein the film is folded two or more times such that at least one semiconductor chip is interposed between surfaces of the film.
4. (Original) The packaging structure as claimed in claim 1, wherein the package is a tape carrier package (TCP).
5. (Original) The packaging structure as claimed in claim 1, wherein the package is a chip-on-film (COF) package.

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6. (Previously Presented) The packaging structure as claimed in claim 1, wherein the film is folded in a predetermined direction by 180° and is adhered by an adhesive material.
7. (Currently Amended) A method of packaging a device, comprising:
 directly mounting a plurality of semiconductor chips to a film; and
 folding the film in a predetermined direction and packaging the plurality of semiconductor chips in one package.
8. (Original) The method as claimed in claim 7, before step (a), further comprising:
 forming an insulating film; and
 forming a conductive pattern on the surface of the insulating film.
9. (Original) The method as claimed in claim 7, wherein the film is folded two or more times such that at least one semiconductor chip is interposed between surfaces of the film.
10. (Previously Presented) The method as claimed in claim 7, wherein the film is folded by 180° and is adhered by an adhesive material.
11. (Currently Amended) A package for two semiconductor chips, the package comprising a film to a first side of which the two semiconductor chips are directly mounted, wherein the film is folded by 180° in the direction of a second side so as to package the two semiconductor chips in one package.

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12. (Original) The package as claimed in claim 11, wherein the film comprises:
 - an insulating film; and
 - a conductive pattern formed on the surface of the insulating film.
13. (Original) The package as claimed in claim 11, wherein the film is folded two or more times such that at least one semiconductor chip is interpose between surfaces of the film.
14. (Original) The package as claimed in claim 11, wherein the package is a tape carrier package (TCP).
15. (Original) The package as claimed in claim 11, wherein the package is a chip-on-film (COF) package.
16. (Previously Presented) The package as claimed in claim 11, wherein the film is folded in a predetermined direction by 180° and is adhered by an adhesive material.